

### Top View LEDs

67-21U-UYD8395V1AB1828Z2-2T0C-AM



### Features

#### Lead (Pb) Free Product - RoHS Compliant

- P-LCC-2 package.
- Colored Clear resin.
- Wide viewing angle 120°.
- Inner reflector and white package.
- Qualification according to AEC-Q101 rev C.
- Precondition: Bases on JEDEC J-STD 020D Level 3.
- Automotive reflow profile (IR reflow or wave soldering)
- Compliance with EU REACH.

### Applications

- Automotive Lighting Interior and Exterior.
- Signal and Symbol Luminary.
- Commercial and Industrial Illumination.
- Backlight: LCD, Switches, Push buttons.

## Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Brilliant Yellow	Water Clear

## Absolute Maximum Ratings (Ta=25 °C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	VR	10	V
Forward Current	IF	70	mA
Peak Forward Current (Duty 1/10 @1KHz)	IFP	100	mA
Power Dissipation	Pd	196	mW
Junction Temperature	Tj	125	
Operating Temperature	Topr	-40 ~ +100	
Storage Temperature	Tstg	-40 ~ +110	
Thermal Resistance	Rth J-A	250	K/W
	Rth J-S	150	K/W
ESD (Classification acc. AEC Q101)	ESD <sub>HBM</sub>	2000	V
	ESD <sub>MM</sub>	200	V
Soldering Temperature	Tsol	Reflow Soldering : 260 °C for 30 sec. Hand Soldering : 350 °C for 3 sec.	

## Electro-Optical Characteristics (Ta=25 °C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	Iv	710	---	1800	mcd	I <sub>F</sub> = 20mA
Viewing Angle	2θ <sub>1/2</sub>	---	120	---	deg	
Dominant Wavelength	λ <sub>d</sub>	583	---	595	nm	
Forward Voltage	V <sub>F</sub>	1.80	---	2.80	V	V <sub>R</sub> = 10V
Reverse Current	I <sub>R</sub>	---	---	10	μA	

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength : ±1nm
3. Tolerance of Forward Voltage: ±0.1V

## Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
V1	710	900	mcd	I <sub>F</sub> = 20mA
V2	900	1120		
AA	1120	1400		
AB	1400	1800		

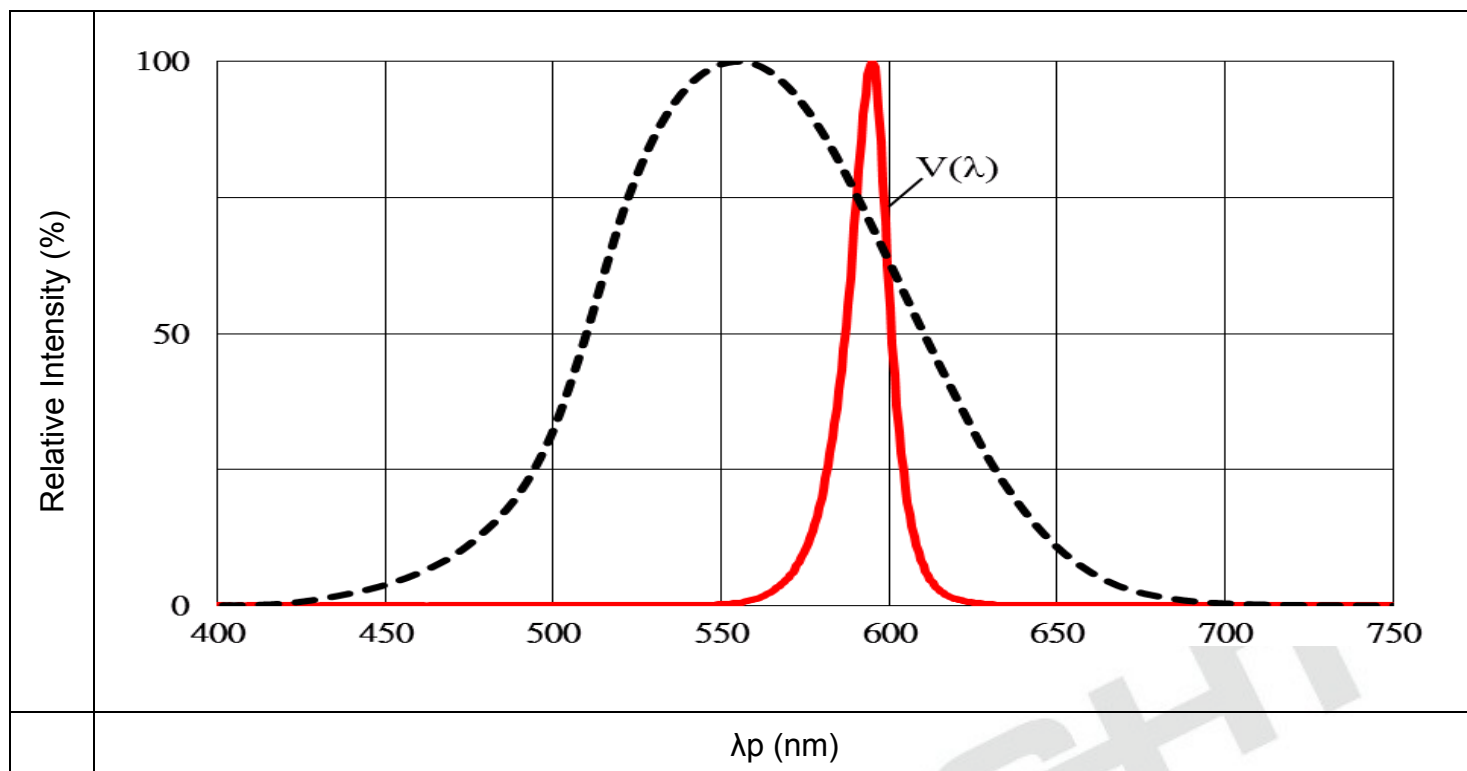
## Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
A5	583	586	nm	I <sub>F</sub> = 20mA
A6	586	589		
A7	589	592		
A8	592	595		

## Bin Range of Forward Voltage

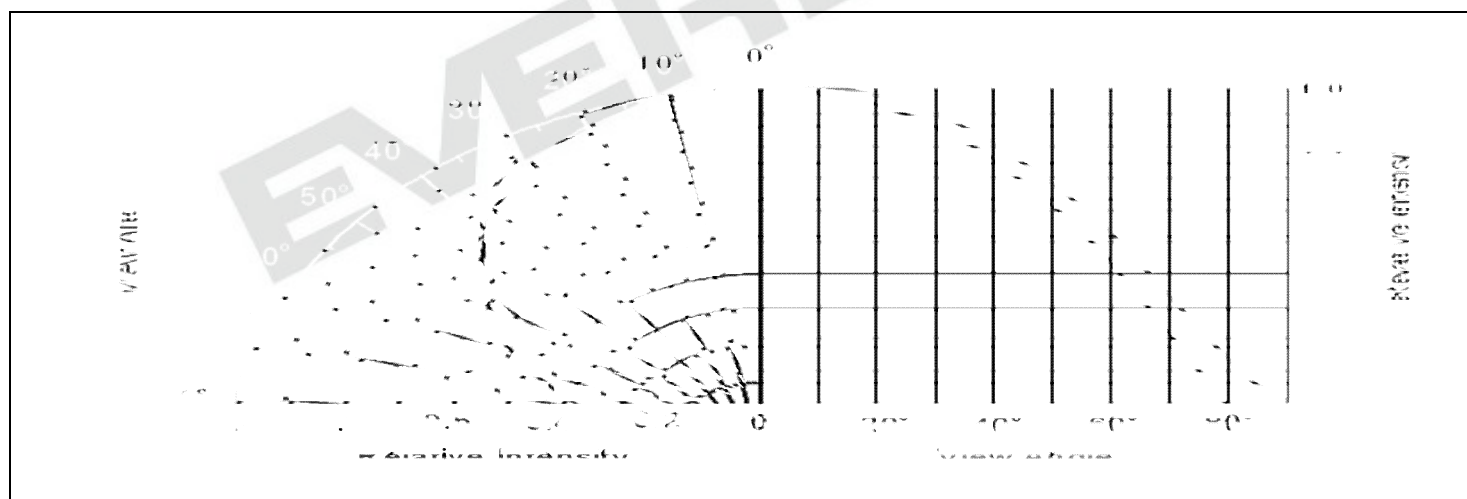
Bin Code	Min.	Max.	Unit	Condition
G3-1	1.80	2.00	V	I <sub>F</sub> = 20mA
G3-2	2.00	2.20		
G3-3	2.20	2.40		
G3-4	2.40	2.60		
G3-5	2.60	2.80		

Typical Electro-Optical Characteristics Curves( $T_a=25^\circ\text{C}$ )  
Typical Curve of Spectral Distribution

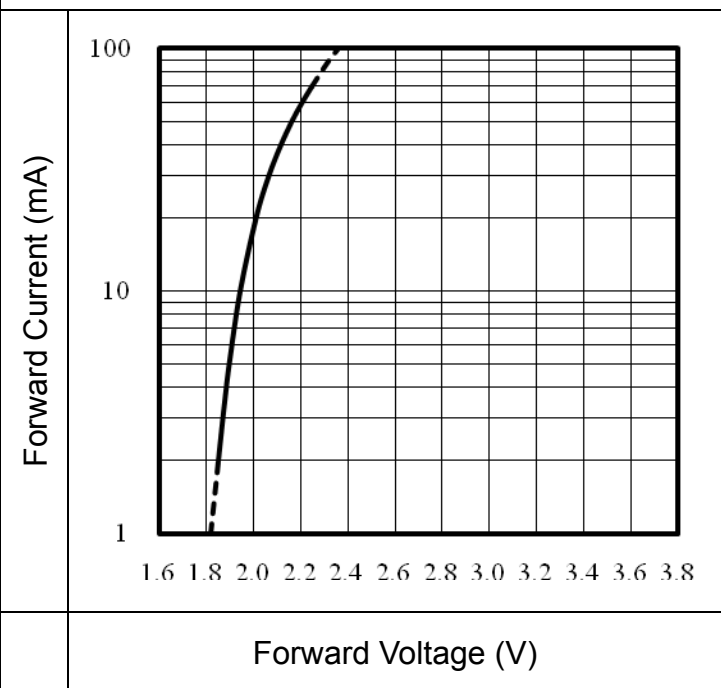


Note:  $V(\lambda)$ =Standard eye response curve;

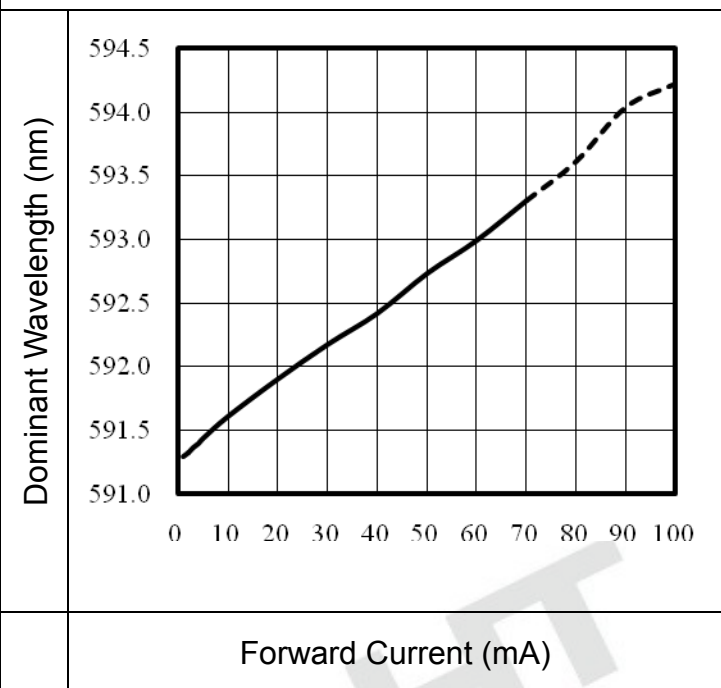
Diagram Characteristics of Radiation



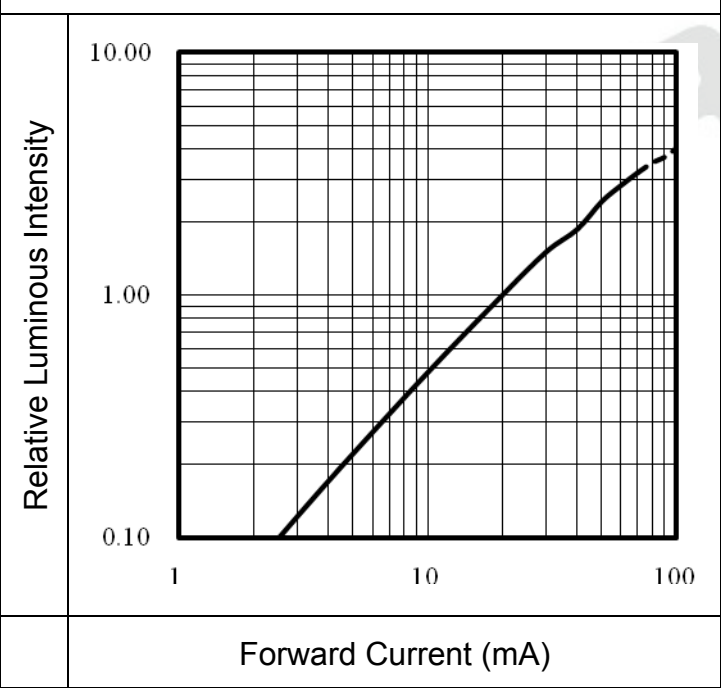
Forward Current vs. Forward Voltage  
(Ta=25 )



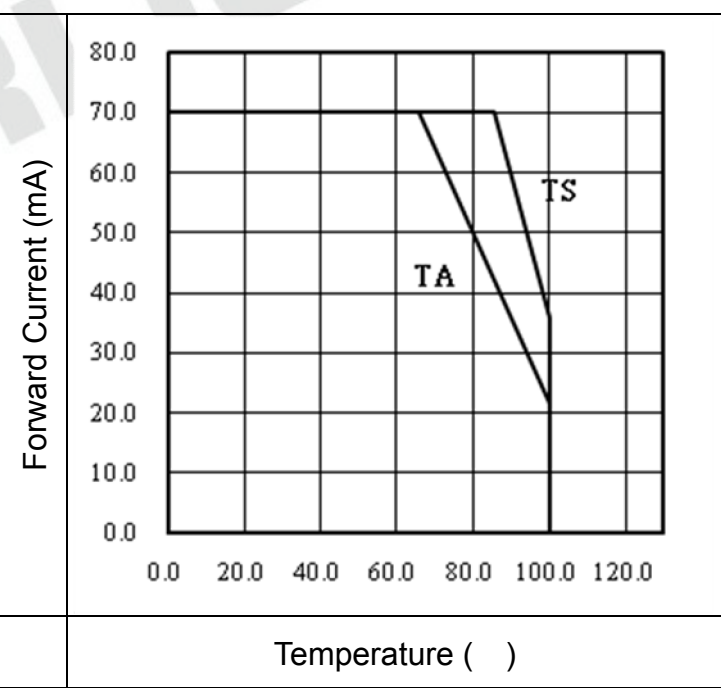
Dominant Wavelength vs. Forward Current  
(Ta=25 )



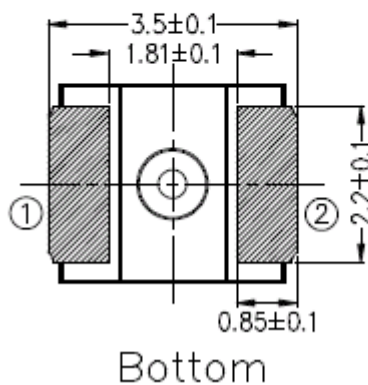
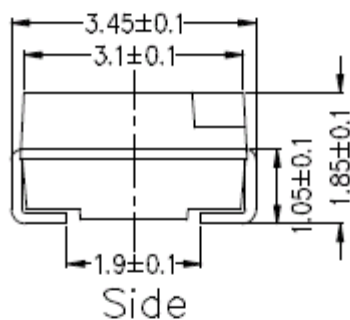
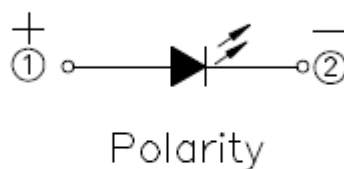
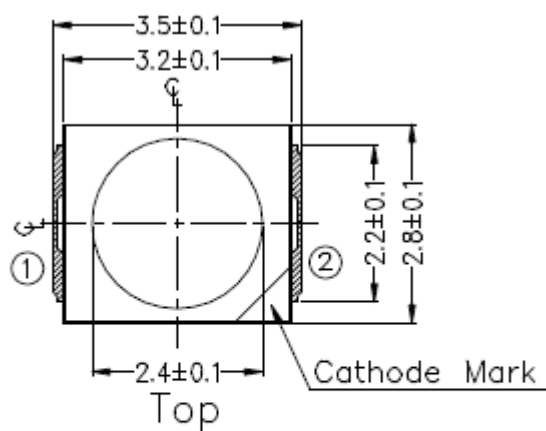
Relative Luminous Intensity vs.  
Forward Current (Ta=25 )



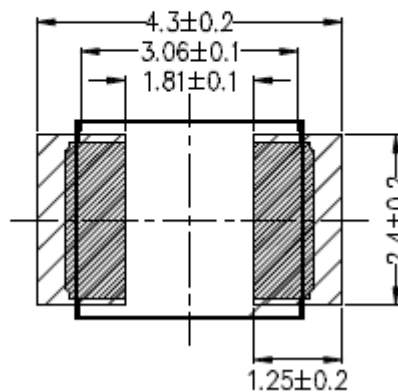
Forward current vs. Ambient and Solder  
Temperature



## Package Dimension



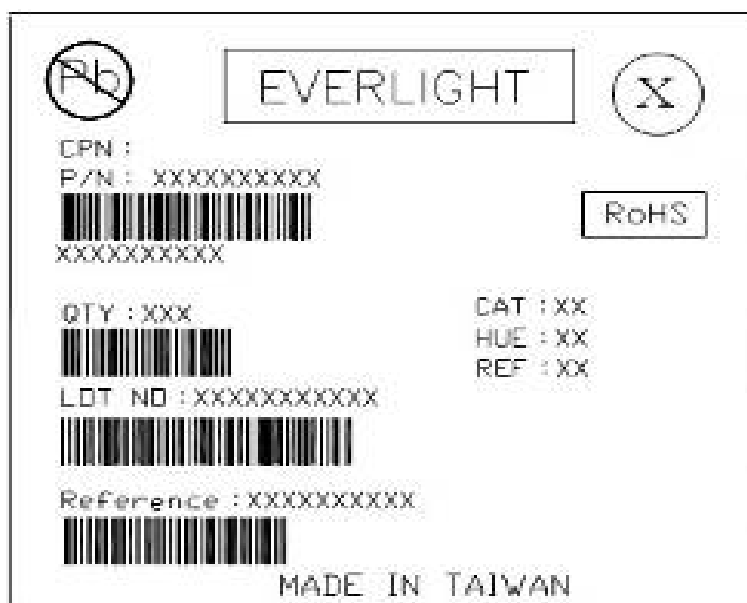
Recommended solder pad



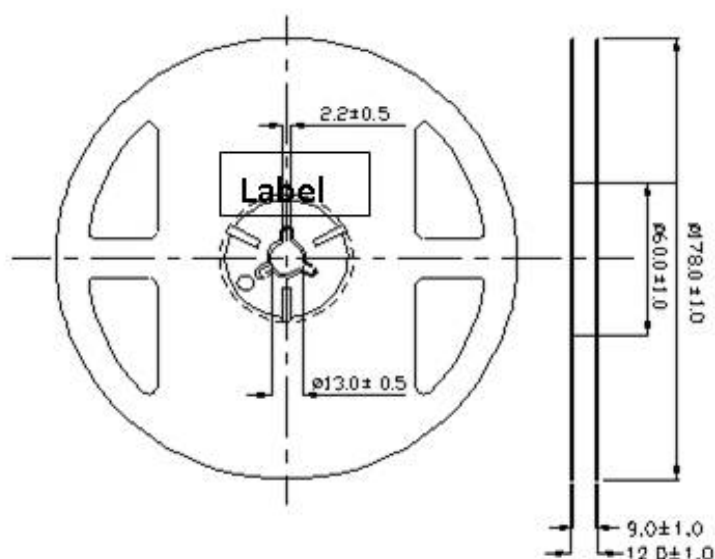
Note: Tolerances unless mentioned  $\pm 0.1$  mm. Unit = mm

## Moisture Resistant Packing Materials Label Explanation

- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

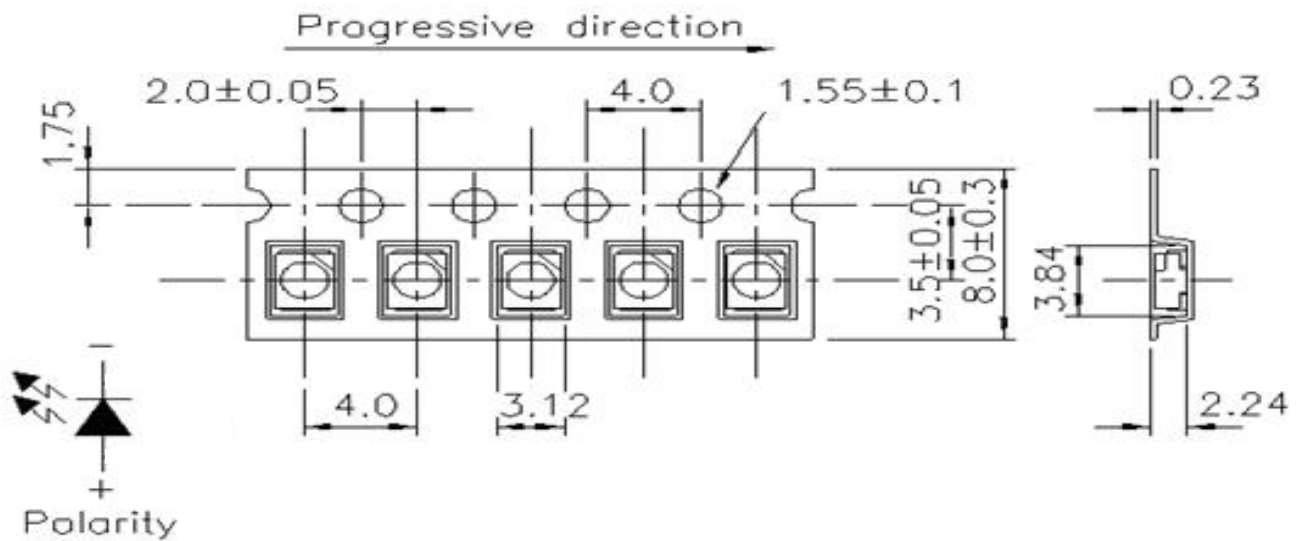


## Reel Dimensions



Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm

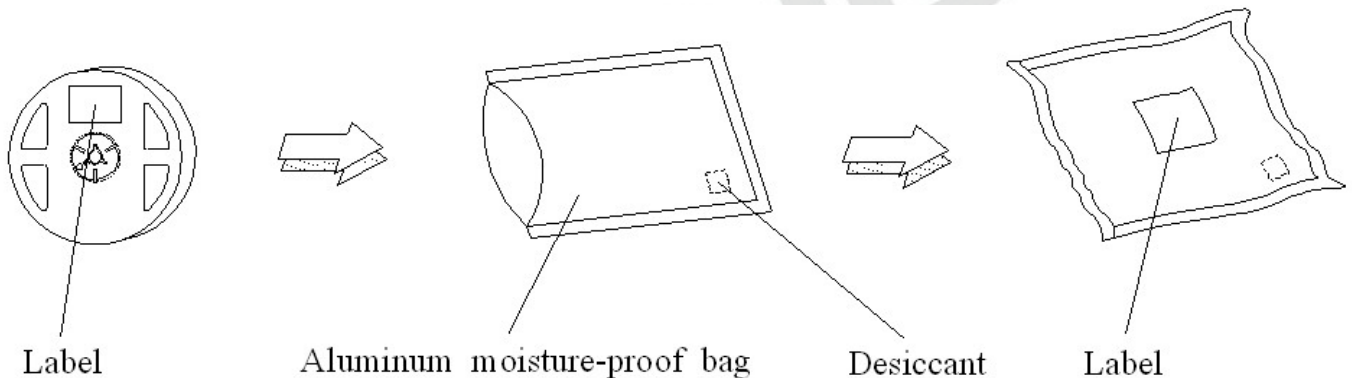
**Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel**



**Note:**

1. Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm
2. Minimum packing amount is 2000 pcs per reel

**Moisture Resistant Packing Process**



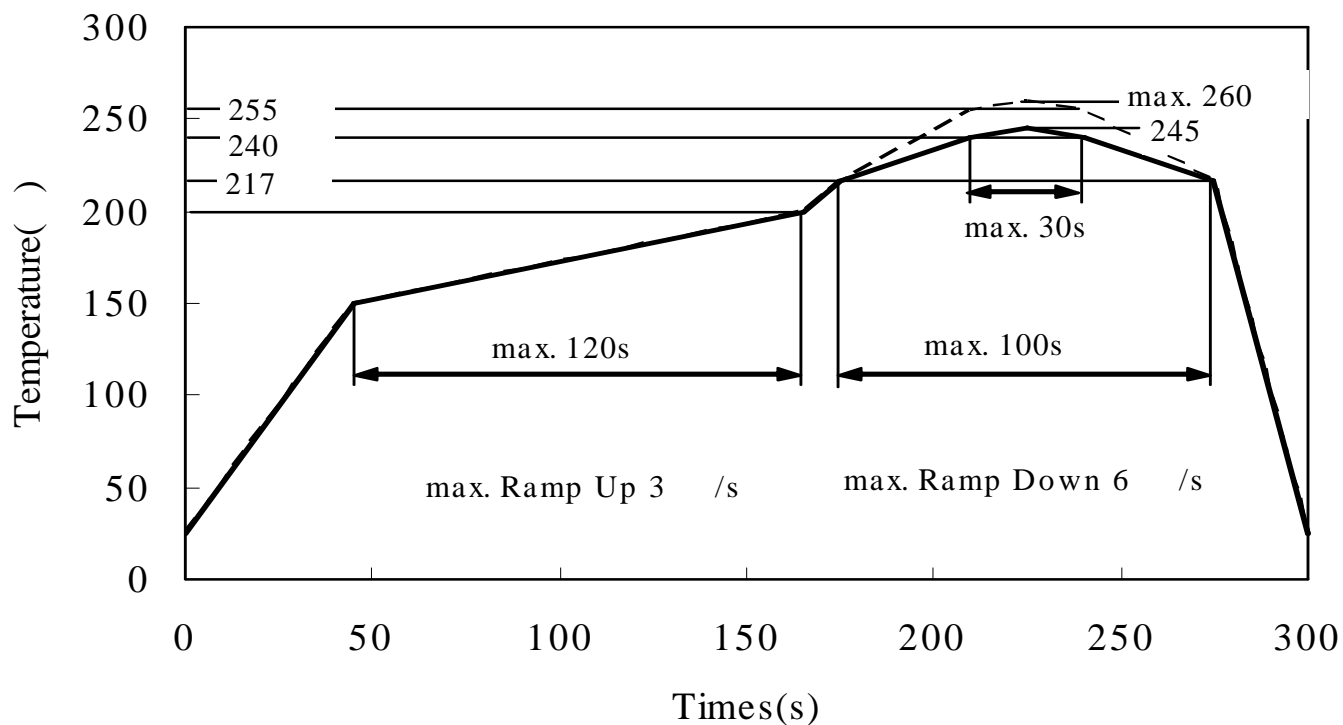
Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm



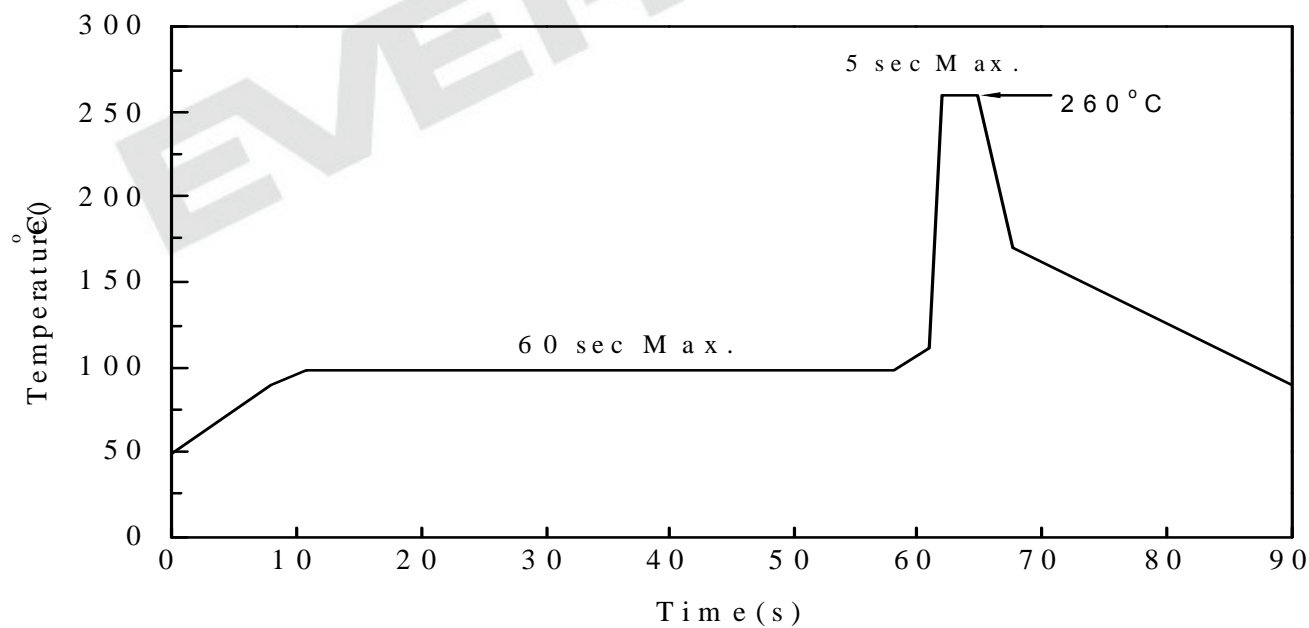
## Precautions for Use

### 1. Soldering Condition (Reference: IPC/JEDEC J-STD-020D)

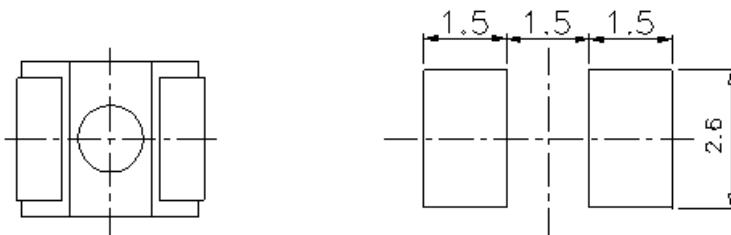
#### a. IR reflow



#### b. Wave soldering reflow



**(B) Recommend soldering pad**



Note: Tolerances unless mentioned  $\pm 0.1\text{mm}$ . Unit = mm

**2. Current limiting**

A resistor should be used to limit current spikes that can be caused by voltage fluctuations. Otherwise damage could occur.

**3. Storage**

- 3.1 Moisture proof bag should only be opened immediately prior to usage.
- 3.2 Environment should be less than 30 °C and 60% RH when moisture proof bag is opened.
- 3.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.
- 3.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

**4. Iron Soldering**

Hand soldering is not recommended for regular production. These guidelines are for rework only. Soldering iron tip should contact each terminal no more than 3 sec at 350 °C, using soldering iron with nominal power less than 25W. Allow min. 2 sec. between soldering intervals.

**5. Usage**

Do not exceed the values given in this specification.

**Application Restrictions**

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.